

# ITA-560NX

## AI Inference Box Computer Powered by NVIDIA® Jetson Orin™ NX for Railway Applications



### Features

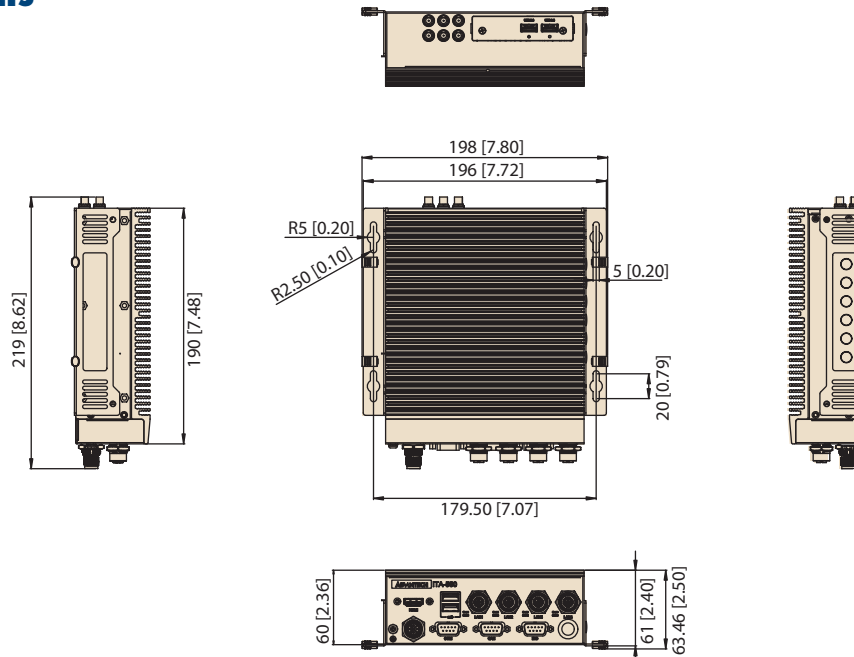
- Fanless box computer designed for AI inference
- Embedded NVIDIA® Jetson Orin™ NX platform
- Compliant with EN 50155 OT1 and EN 50121-3-2 EMC standards
- Rugged M12 connectors suitable for harsh, industrial environments
- 1 x Mini PCIe, 1 x M.2 (E-key), 1 x M.2 (M-key) and 1 x M.2 (B-key) for easy expansion
- Bundled with Linux Ubuntu 20.04 operating system

### Specifications

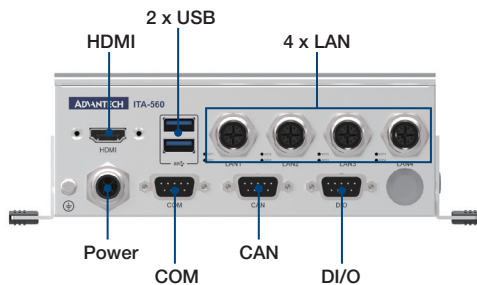
System	GPU	NVIDIA® Ampere GPU 1024 NVIDIA CUDA cores and 32 Tensor cores Up to 100 (Sparse) INT8 TOPs and 50 (Dense) INT8 TOPs
	CPU	NVIDIA® Jetson Orin™ NX 8-core Arm® Cortex®-A78AE v8.2 64-bit CPU
	DLA	20 TOPS each (Sparse INT8)
Memory	Max. Capacity	16 GB 128-bit LPDDR5 102.4 GB/s
I/O - External	Display	1 x HDMI
	CAN	1 x CAN, DB9
	USB	2 x USB 3.0 type A
	Serial Port	1 x RS-232/RS-422/RS-485, DB9
	DI/O	1 x 8bit (4in/4out), DB9
I/O - Internal (Pin Header)	CAN	1 x CAN, DB9 (optional)
	OTG USB	1 x Micro USB
	Serial Port	1 x RS-232/RS-422/RS-485, DB9 (optional)
Ethernet	Controller	Intel® I210-IT
	Interface	10/100/1000 Mbps
	Connector	4 x M12 (X-coded)
Expansion	Mini PCIe	1 x Mini PCIe slot
	M.2	1 x M.2 (B-key) 3052 for 5G/LTE 1 x M.2 (E-key) 2230 for Wi-Fi/Bluetooth 1 x M.2 (M-key) 2280 for storage
	SIM	1 x Nano SIM card slot
	Antenna	6
Power	Input Range	24/110V <sub>DC</sub>
	Connector	1 x M12 (S-coded)
Environmental	Operating Temperature	-25 ~ 55 °C/-13 ~ 131 °F
	Storage Temperature	-40 ~ 85 °C/-40 ~ 185 °F
	Humidity	5% ~ 95% @ 40 °C/104 °F (non-condensing)
Mechanical	Dimensions (W x H x D)	190 x 60 x 160 mm/7.48 x 2.36 x 6.29 in
	Mount Options	Wall mount
Certification	EMC	CE, FCC, BSMI, CCC
	Safety	CE, FCC, BSMI, CCC
EN50155 Compliance	Ambient Temperature	-25 ~ 55 °C/-13 ~ 131 °F (EN 50155 OT1)
	Shock and Vibration	IEC 61373 body mount class B
	Voltage Interruptions	Class S2
	Supply Change Over	Class C1
	EMC	EN 50121-3-2

## Dimensions

Unit: mm [inch]



## I/O Layout



## Ordering Information

Part Number	Processor	Voltage (M12-S-Male)	Ethernet GbE (M12-X-F)	USB 3.1 (Type A)	Mini PCIe	M.2 (M-Key)	M.2 (E-key)	M.2 (B-key)	CAN	COM	DI/O	HDMI
ITA-560NX-LOA1	Orin NX	24V <sub>DC</sub>	4	2	1	1	1	1	1	1	1	1
ITA-560NX-SOA1	Orin NX	110V <sub>DC</sub>	4	2	1	1	1	1	1	1	1	1

## Optional Expansion Modules

Part Number	Description
AIW-355DQ-E01	Qualcomm SDX55 5G M.2 3052 module (EU)
AIW-355DQ-C01	Qualcomm SDX55 5G M.2 3052 module (China)
AIW-355DQ-N01	Qualcomm SDX55 5G M.2 3052 module (US)
AIW-152BQ-001	M.2 2230 802.11AC + BT4.2 i-temp module
SQF-C3AV1-128G-EDE	M.2 2230 OPAL 720 128 GB 3D TLC BiCS3 module (-40 ~ 85 °C/-40 ~ 185 °F)
EWM-W158F01E	802.11 a/b/g/n, Atheros AR9592-AR1B, 2T2R module (wide temperature)
PCM-27D24DI-AE*	Isolated digital I/O module with 16 DI and 8 DO, 1 x mPCIe, and 1 x DB37

\* Requires a specific chassis

## External Cables and Connectors

Part Number	Description
FRU-ITA5831-0002	External cable - Power to M12
FRU-ARS2600-0001	External cable - RJ45 to M12
Y5D5231005	External connector - LAN X-coded
Y5A5231004	External connector - PWR S-coded